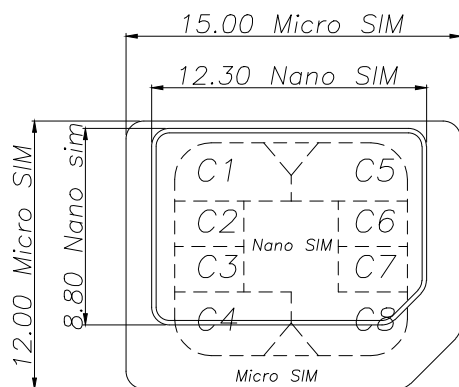
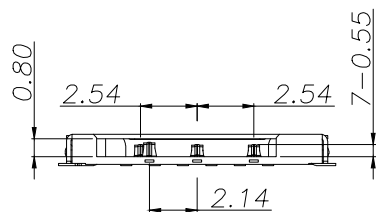
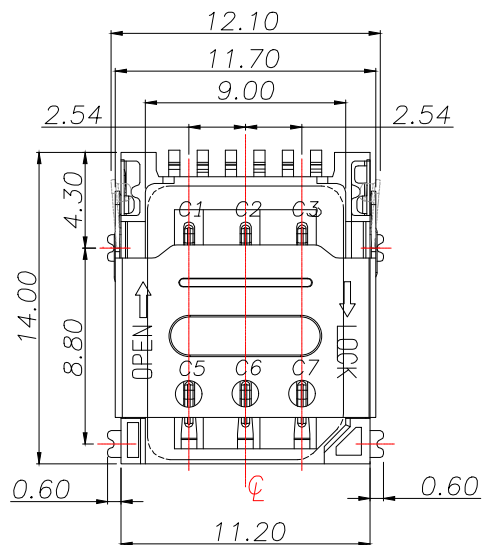
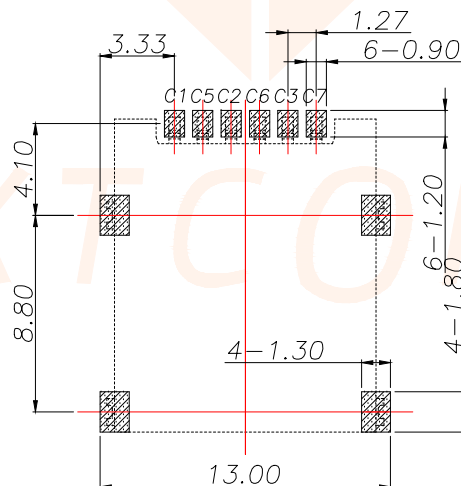
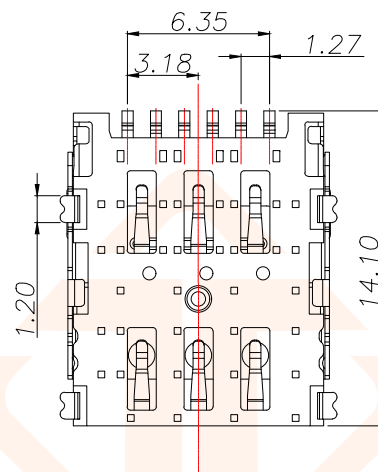
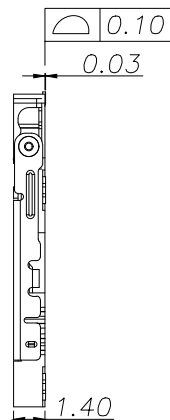
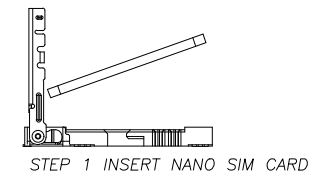




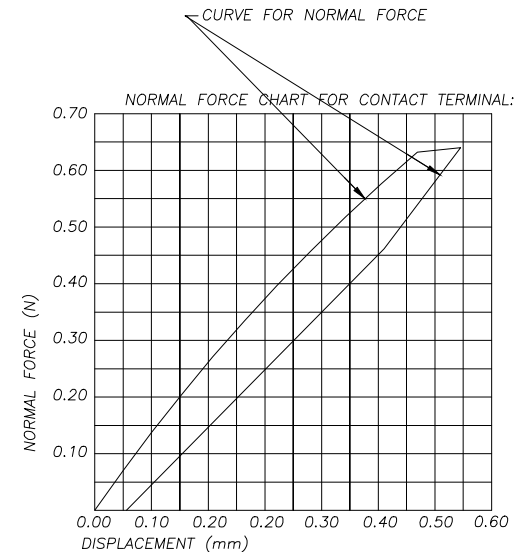
NANO SIM CARD	
Pin No.	NAME
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	I/O OF SIM
C4/C8	N/A



PAD AREA
KEEP OUT AREA

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ± 0.05

REV.	ECN NO.	DESCRIPTION	DATE	DESIGN



NOTES:

1.MATERIAL:

1.1 Housing:High Temperature Thermoplastic
UL94V-0; Color Black.

1.2 Terminal:Copper Alloy,T=0.12mm.

1.3 Shell:Stainless Steel,T=0.20mm.

2.FINISH:

2.1 Terminal:Plated Gold on The Contact Area
and Solder Tails

2.2 Peg:Plated Gold on the bottom of the Solder Tails,
Tin Plated over all.

3.SPECIALITY:

3.1 Rated current:0.5A

3.2 Rated voltage:50V

3.3 Contact Resistance:80mQMAX

3.4 Insulation Resistance:100MQMIN 100V DC

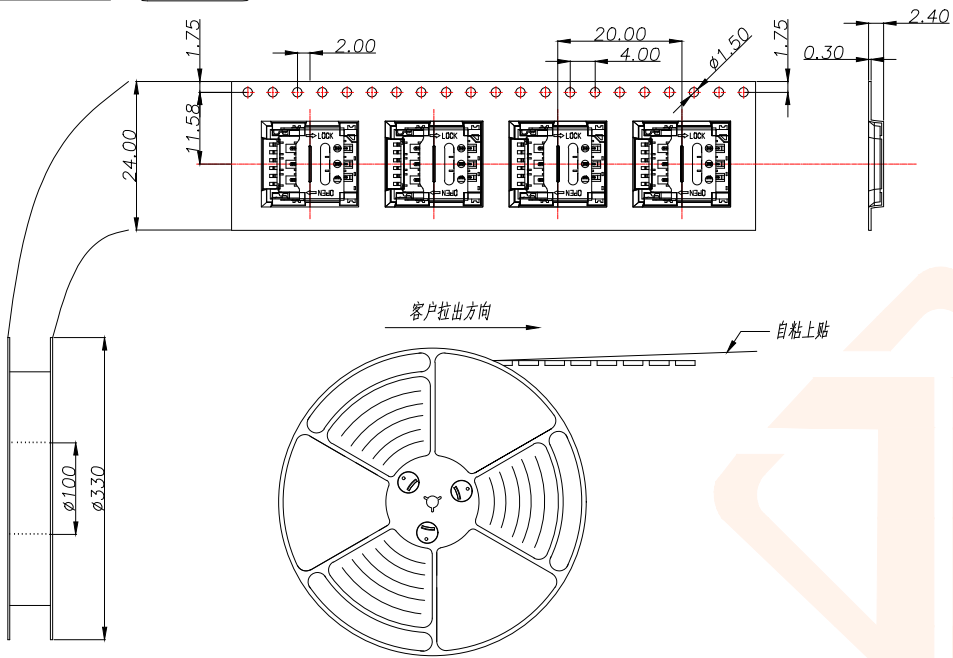
3.5 Dielectric withstanding voltage: 100V AC.

3.6 Solder ability:245 $\pm$ 5°C,5 $\pm$ 0.5s.

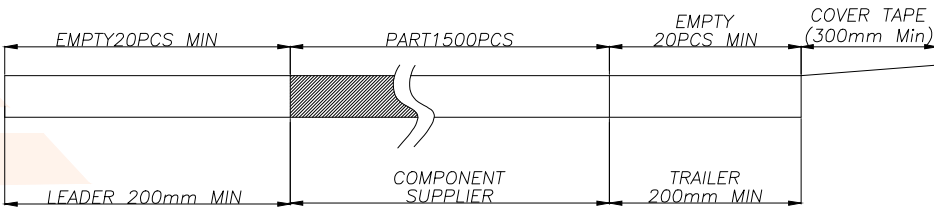
3.7 Operating condition:Temperature: -40°C~+85°C
Humidity: 80% R.H MAX

③	TERMINAL	6	C5210—EH,T=0.12	G/F PLATING	
②	BASE INSULATOR	1	LCP+GF30%	BLACK	
①	SHELL	1	SUS304—H,T=0.15	AU/Ni PLATING	
NO.	PART NAME	Q'TY	DESCRIPTION	NOTE	
TOLERANCE		深圳聚兴泰电子科技有限公司 Shenzhen Juxingtai Electronic Technology Co., Ltd			
X.±0.50	X.±2°	PART NO. JXT—CSIM—305—XG6P		TITLE: 6PIN 1.4H HINGE NANO SIM CARD CONN	
X.X±0.20	X.X°±1°				
X.XX±0.10					
UNITS	mm	DESIGN: Ethan		MANUFACTURE DWG	
MATERILA	— — —	CHED: Olvia			
FINISH	— — —	APPD: Ava			SCALE N:A
				SHEET 1/2	

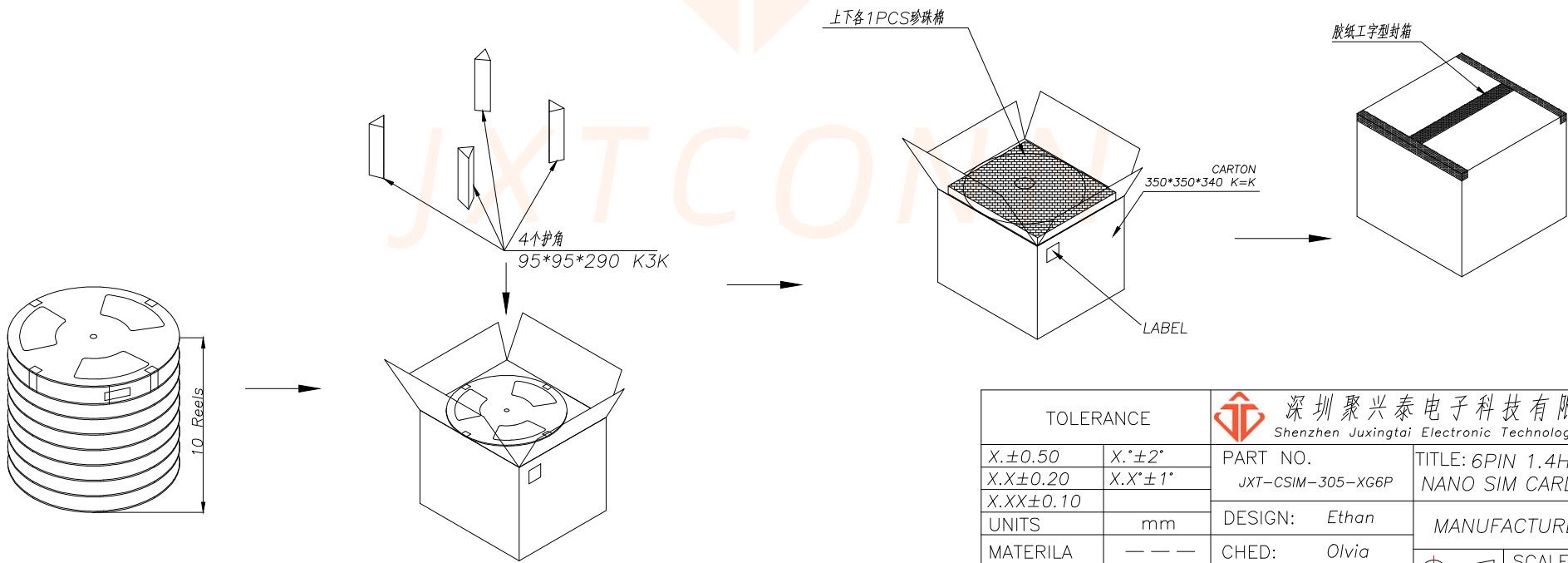
REV.	ECN NO.	DESCRIPTION	DATE	DESIGN



- NOTES
1. NUMBER OF CONNECTORS:1500PCS/REEL
 2. LEAD TAPE LENGTH



3. QUANTITY:15000PCS/CARTON



TOLERANCE		深圳聚兴泰电子科技有限公司 Shenzhen Juxingtai Electronic Technology Co., Ltd		
X.±0.50	X.*±2°	PART NO. JXT-CSIM-305-XG6P	TITLE: 6PIN 1.4H HINGE NANO SIM CARD CONN.	
X.X±0.20	X.X°±1°			
X.XX±0.10				
UNITS	mm	DESIGN:	Ethan	MANUFACTURE DWG
MATERILA	---	CHED:	Olvia	
FINISH	---	APPD:	Ava	
				SCALE N:A
				SHEET 2/2